

3EC-M1S-VLP

- 無載體箔之 $7\mu\text{m}$ 薄銅箔, 具高抗張力特性。
Thin foil ($7\mu\text{m}$), high tensile strenght, supply without carrier foil.
- 極低粗糙度電解銅箔, 適用於極細線路蝕刻之減成法製程。
Low profile copper foil, suitable for fine etching in the subtractive process.

用途/Application

- 軟性電路板
/Flexible Print Board

構成/Composition



生產地點/Production Site

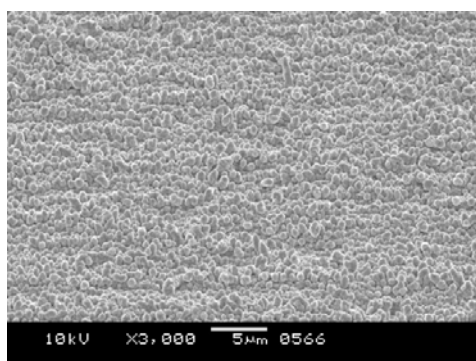
- 日本/Japan

代表性特性數據/Representive

	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elogation (%)	Peel Strength (kg/cm)@FR-4
3EC-M1S-VLP	7	64	1.8	500	4	0.7

※上述表列為代表性數據非保證值
This is representative data, not guaranteed.

處理面/Laminate side



阻劑面/ resist side

